



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION OF

ASAI et al.

Group Art Unit: 2841

Appln. No.: 09/529,597

Examiner: H. Bui

Filed: May 31, 2000

Title: PACKAGE SUBSTRATE

December 13, 2001

\* \* \* \* \*

AMENDMENT

Hon. Commissioner of Patents  
Washington, D.C. 20231

Sir:

Responsive to the Office Action mailed on September 13, 2001, please amend the  
patent application identified above as follows:

IN THE CLAIMS:

Please amend claim 1 as follows:

1. A package board having a core board on each surface of which a plurality of  
conductor circuits are formed with an interlaminar resin insulating layer therebetween,  
wherein a plurality of soldering pads are formed <sup>on an IC chip</sup> ~~on the IC chip~~ mounted side surface, as well  
<sup>as on an other side surface</sup> ~~as on the other side surface~~ to be connected to another board, so that said soldering pads on  
the other side surface are larger than those on said IC chip side surface of said package board,  
and  
12/18/2001 RTYSON 00000001 033975 09529597  
01 FC:102 168.08 dummy pattern for improving the mechanical strength of the package board is  
formed between signal line conductor circuit patterns formed on said IC chip mounted side  
surface of said core board.

420

B

#17/Andt B  
R. Tyson  
12/18/01  
RECEIVED  
DEC 17 2001  
TC 2800 MAIL ROOM

10/18/01

C  
B1